



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*


Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-08-07
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L79L12ACUTR	MF39*LB12FC2	A	Z8GA	2015-08-07
Amount		UoM	Unit type	ST ECOPACK Grade
59.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SOT	4.5X2.45X1.5	4	gull wing	
Comment	Package: SOT 89			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	MF39*LB12FC2					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	0.902	mg	supplier	die	Silicon (Si)	7440-21-3		0.882	mg	977852	14966
				supplier	metallization	Aluminium (Al)	7429-90-5		0.011	mg	12182	186
				supplier	Passivation	Silicon Nitride	12033-89-5		0.004	mg	4430	68
				supplier	Passivation	Silicon Oxide	7631-86-9		0.005	mg	5537	85
Leadframe	Copper and its alloy	31.791	mg	supplier	Alloy	Copper(CU)	7440-50-8		31.559	mg	992702	534898
				supplier	Alloy	Iron(Fe)	7439-89-6		0.032	mg	1007	542
				supplier	Alloy	Phosphorus(P)	7723-14-0		0.010	mg	315	169
				supplier	metallization	Silver(Ag)	7440-22-4		0.190	mg	5977	3220
Die attach	Other organic materials	0.200	mg	supplier	Glue	Silver(Ag)	7440-22-4		0.148	mg	740000	2508
				supplier	Glue	Epoxy Resin	proprietary		0.030	mg	150000	508
				supplier	Glue	Aliphatic anhydride	proprietary		0.014	mg	70000	237
				supplier	Glue	2-Butoxyethyl acetate	112-07-2		0.004	mg	20000	68
Bonding wire	Precious metals	0.048	mg	supplier	Glue	Polymeric material	proprietary		0.004	mg	20000	68
				supplier	Bonding wire	Gold(Au)	7440-57-5		0.048	mg	1000000	814
				supplier	Molding compound	Silica Fused	60676-86-0		21.955	mg	882010	372119
				supplier	Molding compound	Epoxy,Cresol Novolac	29690-82-2		0.374	mg	15025	6339
Encapsulation	Other organic materials	24.892	mg	supplier	Molding compound	Phenol Resin	25068-38-6		1.244	mg	49976	21085
				supplier	Molding compound	Epoxy Resin	29690-82-2		1.244	mg	49976	21085
				supplier	Molding compound	Carbon Black	1333-86-4		0.075	mg	3013	1271
				supplier	Connections coating	Tin(Sn)	7440-31-5		1.167	mg	1000000	19780